



PATENT
Attorney Docket No.: COOL-01800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kenneth Goodson et al.

Serial No.: 10/698,304

Filed: October 30, 2003

For: **METHOD AND APPARATUS FOR
ACHIEVING TEMPERATURE
UNIFORMITY AND HOT SPOT
COOLING IN A HEAT
PRODUCING DEVICE**

) Group Art Unit: 3753

) Examiner:

) **TRANSMITTAL LETTER**

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

Enclosed please find an Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #60113); (EFS ID #60115); (EFS ID #60117) and (EFS ID #60119) filed on April 29, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 4-29-04

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CERTIFICATE OF MAILING (37 CFR § 1.8(a))

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Date: 4-30-04 By: John A. Haverstock



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)	162 N. Wolfe Road
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COOLING IN A HEAT)	
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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #60113); (EFS ID #60115); (EFS ID #60117) and (EFS ID #60119). Applicants have become aware of the following printed publication which may be material to the examination of this application:

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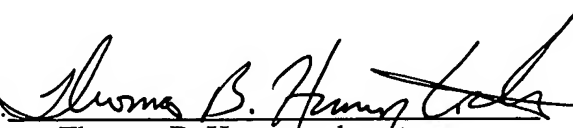
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Respectfully submitted,
HAVERSTOCK & OWENS LLP

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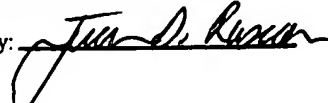
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT
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Applicants: Kenneth Goodson et al.

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Filing Date: October 30, 2003

Group Art Unit: 1312

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